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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : Randy H. Y. LO, Chi-Chuan WU and Ssu-Cheng LAI
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For : METHOD OF PACKAGING MULTI CHIP MODULE

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R. Stokes

Honorable Commissioner of Patents
and Trademarks
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Sir:

I/We am (are) not aware of any additional documents material to the examination of the above-identified patent application.

Respectfully submitted

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